

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPP060N06N	**Issued**	24. February 2022
MA#	MA005708521		
Package	PG-TO220-3-1	**Weight***	2033.87 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.049	0.05	0.05	516	516
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		401	
	non noble metal	copper	7440-50-8	815.335	40.10	40.15	400879	401400
wire	non noble metal	aluminium	7429-90-5	4.138	0.20	0.20	2035	2035
encapsulation	inorganic material	zincoxide	1314-13-2	5.992	0.29		2946	
	miscellaneous	miscellaneous	-	23.968	1.18		11784	
	plastics	epoxy resin	-	89.879	4.42		44191	
	inorganic material	silicondioxide	60676-86-0	479.355	23.57	29.46	235686	294607
leadfinish	non noble metal	tin	7440-31-5	21.462	1.06	1.06	10552	10552
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121
solder	non noble metal	tin	7440-31-5	0.023			11	
	noble metal	silver	7440-22-4	0.029			14	
	non noble metal	lead	7439-92-1	1.102	0.05	0.05	542	567
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		290	
	non noble metal	copper	7440-50-8	589.466	28.98	29.02	289825	290202
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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